RENESAS ZSC31050 / ZSC31150 / ZSSC313X / ZSSC3154 / ZSSC3170 Application Note - RBIC1 Calibration DLL

Contents

RB	BIC1 Dynamic-Link Library (DLL)	2
Cal	alibration Sequence	
2.1.	Set-up and Initialization	4
2.2.	Data Collection	5
2.3.	Coefficient Calculation	6
2.3.	3.1. Function Call for Main Sensor Channel	6
2.3.	3.2. Function Call for Temperature Channel	7
2.3.	3.4. Calculation Examples	10
	•	
	C: 2.1. 2.2. 2.3. 2.3 2.3 2.3 2.3 2.4. 2.5. G	RBIC1 Dynamic-Link Library (DLL) Calibration Sequence 2.1. Set-up and Initialization 2.2. Data Collection 2.3. Coefficient Calculation 2.3.1. Function Call for Main Sensor Channel 2.3.2. Function Call for Temperature Channel 2.3.3. Returned Error Codes 2.3.4. Calculation Examples 2.4. EEPROM Programming 2.5. Verification Glossary Document Revision History

List of Figures

Figure 1.1	SSC Block Diagram and Signal Flow for a Pressure Sensor Example	3
Figure 2.1	Basic Analog Front-End	4
Figure 2.2	Calibration Points	5
Figure 2.3	Calibration Points and Target Values for Sensor Measurements	6
Figure 2.4	Calibration Points and Target Values for Temperature Measurement	8
Figure 2.5	Calculation and Measurement Results	11

List of Tables

Table 1.1	Coefficients that Result from ZMD31050_cal1	. 2
Table 2.1	List of Calibration Parameters	6
Table 2.2	List of Temperature Calculation Function Parameters	.7
Table 2.3	Returned Error Codes	9

1 RBIC1 Dynamic-Link Library (DLL)

The calibration DLL described in this document is designed to expedite the calibration process for the ZSC31050, ZSC31150, ZSC313x, ZSSC3154, and ZSSC3170 Sensor Signal Conditioner (SSC) products. Unless otherwise noted, the term SSC IC will be used in this document to refer to these five products.

The calibration process compensates the sensor input offset, sensor linearization, and sensor's sensitivity temperature dependency. It uses a polynomial function called *ZMD31050_cal1*, which calculates coefficients for up to 3rd order linearization compensation and up to 2nd order for the temperature compensation. The *RBIC1 DLL* is contained in the Evaluation Software installation folder.

Coefficients resulting from ZMD31050_cal1 are stored in the SSC EEPROM memory. Table 1.1 provides a list of the resulting coefficients.

Coefficient Name	EEPROM Address	Polynomial Function	Description
C0	00 _{HEX}	Offset	Input signal when no sensor excitation is present
C1	01 _{HEX}	Gain Sensor signal gain value	
C2	02 _{HEX}	Linearization	2 nd order non-linearity for three-point calibration
C3	03 _{HEX}	Linearization	3 nd order non-linearity for four-points calibration
C4	04 _{HEX}	Temperature compensation	1 st order temperature coefficient sensor offset
C5	05 _{HEX}	Temperature compensation	2 st order temperature coefficient sensor offset
C6	06 _{HEX}	Temperature compensation	1 st order temperature coefficient gain dependency
C7	07 _{HEX}	Temperature compensation	2 st order temperature coefficient gain dependency

 Table 1.1
 Coefficients that Result from ZMD31050_cal1

Figure 1.1 illustrates a typical signal flow from measuring the physical value to the output of the conditioned result with offset compensation and gain compensation to meet the voltage output targets and signal linearization requirements for the application.

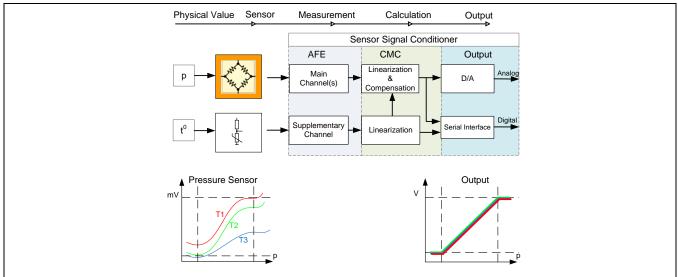


Figure 1.1 SSC Block Diagram and Signal Flow for a Pressure Sensor Example

2 Calibration Sequence

A typical calibration flow contains five steps in the following order:

- 1. Set-up and initialization
- 2. Data collection
- 3. Coefficient calculation
- 4. EEPROM programming
- 5. Verification

These five steps are very similar for all applicable products; there might be some insignificant differences in the Evaluation Software user interface.

Connect the SSC IC to the user's PC using the selected interface applicable to the product: I²C[™]*, OWI, LIN, or SPI. Refer to the product's *Functional Description* document for the available command set.

* I^2C^{TM} is a trademark of NXP.

2.1. Set-up and Initialization

Prior to data collection, the SSC must to be configured so that the analog front-end (AFE), temperature measurement, and additional SSC functions fit the sensor's parameters and application requirements. This includes gain selection, sensor signal range, ADC resolution, temperature sensor in use, output format, and diagnostic functions.

The goal is to adjust the gain so the sensor signal is as close as possible to the acceptable ADC voltage range for the full operational temperature range. For this, the sensor span, offset, and tolerances must be taken into account.

Next, write the initial configuration into the RAM or the EEPROM of the SSC IC.

Note: Setting initial coefficients values is not required (initially coefficients can be set to 0 or any value).

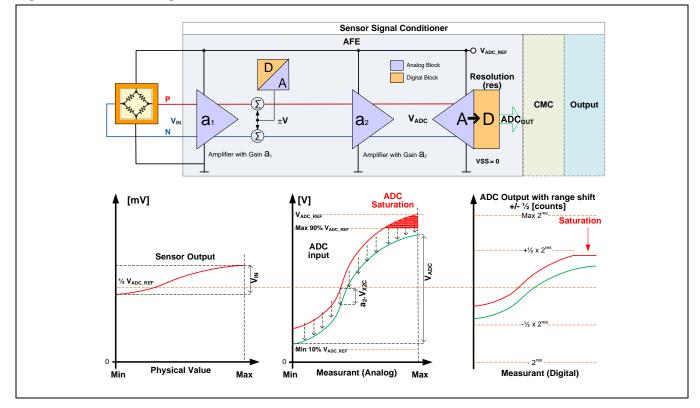
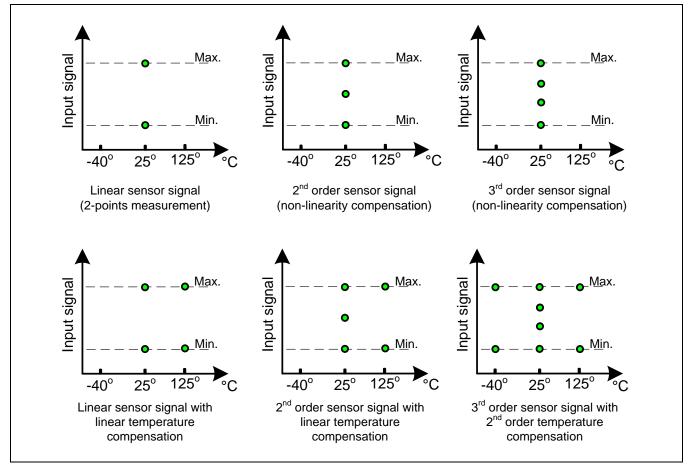


Figure 2.1 Basic Analog Front-End

2.2. Data Collection

After the coefficients in EEPROM are initialized, data collection can begin. The minimum number of calibration points required varies between two and as many as eight for the main sensor and two or three for the temperature sensor. This depends on the precision required and the behavior of the sensor in use. In general, taking more calibration points will result in a better calibration.

Figure 2.2 shows the expected placement of calibration points for the different calibration options. The order of the points taken is not important; however, the number of points per temperature must be followed or the calibration might fail. The location and order of the temperature values is also not important – however for best results, the temperatures should be spread evenly throughout the user's specification range. It is important to keep the calibration points as orthogonal as possible to maximize calibration accuracy.





The calibration point configuration can be any setup from 2-points linear calibration to 3rd order non-linearity compensation and 2nd order temperature dependency compensation.

2.3. Coefficient Calculation

2.3.1. Function Call for Main Sensor Channel

ZMD31050_cal1 (Zp1m, Zp2m, Zp4m, Zp3m, Zp1u, Zp2u, Zp1l, Zp2l, A, B, M2, M, Ztmed, Ztupp, Ztlow, adc_res, &C0, &C1, &C2, &C3, &C4, &C6, &C5, &C7);

Figure 2.3 Calibration Points and Target Values for Sensor Measurements

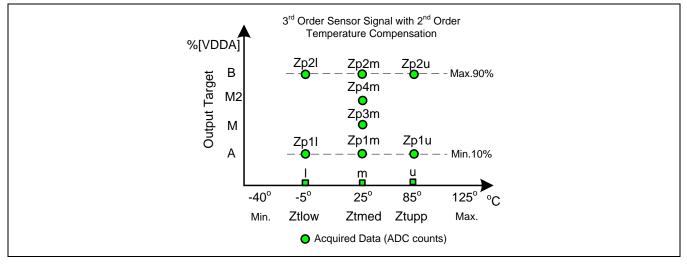


Table 2.1	List of Calibration	Parameters
-----------	---------------------	------------

Name	Description	Туре	Range	lf not used	Condition	
ZMD31050_cal1	Function call, main sensor channel	int	4 bytes		Returns 0 if successful	
Zp1m	Sensor minimum output	float	±2 ¹⁵	Required		
Zp2m	Sensor maximum output	float	±2 ¹⁵	Required	Madium tomporatura	
Zp3m	Sensor output (2nd order nonlinearity)	float	±2 ¹⁵	0	Medium temperature	
Zp4m	Sensor output (3rd order nonlinearity)	float	±2 ¹⁵	0		
Zp1u	Sensor minimum output	float	±2 ¹⁵	0		
Zp2u	Sensor maximum output	float	±2 ¹⁵	0	Upper temperature	
Zp1I	Sensor minimum output	float	±2 ¹⁵	0		
Zp2l	Sensor maximum output	float	±2 ¹⁵	0	Lower temperature	
А		float	0 to 1	Required		
М	Target output value in [%] multiplied by	float	0 to 1	0		
M2	0.01 for digital output target 0.006875 for analog output target	float	0 to 1	0	A < M < M2 < B	
В		float	0 to 1	Required		

© 2019 Renesas Electronics Corporation

Name	Description	Туре	Range	lf not used	Condition
Ztmed	Temperature sensor	float	±2 ¹⁵	-33000.0	Medium temperature
Ztupp	Temperature sensor	float	±2 ¹⁵	-33000.0	Upper temperature
Ztlow	Temperature sensor	float	±2 ¹⁵	-33000.0	Lower temperature
adc_res	ADC resolution	int	9 to 16	-	Given in bits
C0 to C7	Calculated coefficients	float	4 bytes	0	Results upon success

Data acquisition commands: $D8_{HEX}$ for sensor and $D9_{HEX}$ for calibration temperature.

Command format: [7bit Slave Address] [0] [8-bit command]

Evaluation software command:

I²C[™] interface: IW_78001**D8** OWI interface: OW_78001**D8** LIN interface: LW_3c0087F05B4**D8**FFFFFFF

2.3.2. Function Call for Temperature Channel

TQuad (Ztlow, Ztupp, Ztmed, Tlow, Tupp, Tmed, adc_res, &Ct0, &Ct1, &Ct2);

TLin (Ztmed, Ztupp, Tmed, Tupp, &Ct0, &Ct1);

Table 2.2 List of Temperature Calculation Function Parameters

Name	Description	Туре	Range	Condition
TQuad	Function call, temperature channel 2 nd order	bool		Returns 0 if successful
TLin	Function call, temperature channel linear	bool		Returns 0 if successful
Ztmed	Temperature sensor	float	±2 ¹⁵	Medium temperature
Ztupp	Temperature sensor	float	±2 ¹⁵	Upper temperature
Ztlow**	Temperature sensor	float	±2 ¹⁵	Lower temperature
Tlow	Target value calculated by:	float	0 to 1	$temp_{range} = T_{low} - T_{min}$
Tmed	$temp_{range} * \frac{Target_{max} - Target_{min}[\% VDDA]}{Target_{max} - Target_{min}[\% C]} + \frac{Target_{min}[\% VDDA]}{100}$	float	0 to 1	$temp_{range} = T_{med} - T_{min}$
Тирр	Where VDDA stands for analog power supply and ADC reference voltage of the IC.	float	0 to 1	$temp_{range} = T_{upp} - T_{min}$
adc_res	ADC resolution, temperature channel	int	9 to 16	Given in bits
Ct1 to Ct3	Calculated coefficients, temperature channel	float	4 bytes	Result upon success

Data acquisition commands: **DA_{HEX}**

Command format: [7bit Slave Address] [0] [8-bit command]

Evaluation Software Command:

I²C[™] interface: IW_78001**DA** OWI interface: OW_78001**DA** LIN interface: LW_3c0087F05B4**DA**FFFFFFF

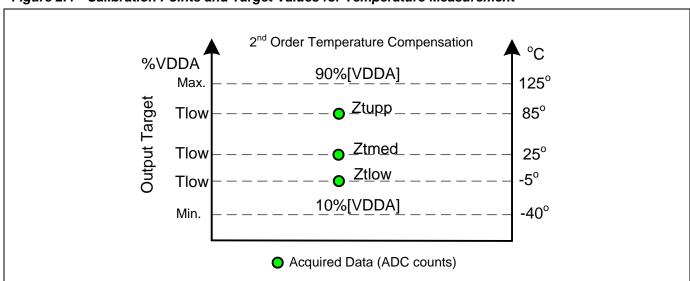


Figure 2.4 Calibration Points and Target Values for Temperature Measurement

The upper and lower limits (Max. and Min.) are usually selected as 10% and 90% of the ADC reference voltage (the analog voltage supply). Note that this varies depending on the SSC IC. In this input range, the ADC has the best performance for linearity.

2.3.3. Returned Error Codes

Note: bit [0] is not used

Table 2.3 Returned Error Codes

Flags	HEX	Bit	Description
0000 0000 0000 0010	0002 _{HEX}	bit[1]	No solution found for given input data.
0000 0001 0000 0010	0102 _{HEX}	bit[1] and bit[8]	Calculated coefficients are out of range (linear calibration).
0000 0010 0000 0010	0202 _{HEX}	bit[1] and bit[9]	Offset: No solution found or coefficients are out of range.
0000 0100 0000 0010	0402 _{HEX}	bit[1] and bit[10]	Gain: No solution found or coefficients are out of range.
0000 1000 0000 0010	0802 _{HEX}	bit[1] and bit[11]	2 nd order: No solution found or coefficients are out of range.
0001 0000 0000 0010	1002 _{HEX}	bit[1] and bit[12]	3 rd order: No solution found or coefficients are out of range.
0000 0000 0000 0100	0004 _{HEX}	bit[2]	Range check error.
0000 0001 0000 0100	0104 _{HEX}	bit[2] and bit[8]	Offset compensation error.
0000 0010 0000 0100	0204 _{HEX}	bit[2] and bit[9]	Gain calculation error.
0000 0100 0000 0100	0404 _{HEX}	bit[2] and bit[10]	C1 and C2 calculation error.
0000 0100 0000 0100	0804 _{HEX}	bit[2] and bit[11]	C3 and C4 calculation error.
0000 1000 0000 0100	1004 _{HEX}	bit[2] and bit[12]	C5 calculation error.
0010 0000 0000 0100	2004 _{HEX}	bit[2] and bit[13]	C6 calculation error.
0100 0000 0000 0100	4004 _{HEX}	bit[2] and bit[14]	C7 calculation error.
0000 0000 0000 1000	0008 _{HEX}	bit[3]	Temperature behavior linearization calculation error.
0000 0001 0000 1000	0108 _{HEX}	bit[3] and bit[8]	Offset temperature coefficient calculation (C4 and C5).
0000 0010 0000 1000	0108 _{HEX}	bit[3] and bit[9]	Gain temperature coefficient calculation (C6 and C7).
0000 0000 0001 0000	0010 _{HEX}	bit[4]	Coefficients range check error.
0000 0001 0001 0000	0110 _{HEX}	bit[4] and bit[8]	Coefficient range check (C0 and C1) error.
0000 0010 0001 0000	0210 _{HEX}	bit[4] and bit[9]	Non-linearity coefficient range check (C2 and C3).



2.3.4. Calculation Examples

ADC max.:	90%[VDDA]
ADC min.:	10%[VDDA]
ADC resolution:	14 bit
Data points:	10%, 50%, 70% and 90%
Temperature points:	-40°C, -5°C, 25°C, 85°C and 125°C

- Linear (two points, no non-linearity and temperature compensation) **ZMD31050_cal1** (data #1, data #2, 0, 0, 0, 0, 0, 0, 0, 0, 0, 0, -33000, -33000, -33000, 14, &C0, &C1, &C2, &C3, &C4, &C6, &C5, &C7);
- 2nd order non-linearity compensation (three points at 10%, 50%, and 90%, no temperature compensation) **ZMD31050_cal1** (data #1, data #2, 0, data #3, 0, 0, 0, 0, 0, 1, 0.9, 0, 0.5, -33000, -33000, -33000, 14, &C0, &C1, &C2, &C3, &C4, &C6, &C5, &C7);
- 3rd order non-linearity compensation (four points at 10%, 50%, 70%, and 90%, no temperature compensation) **ZMD31050_cal1** (data #1, data #2, data #4, data #3, 0, 0, 0, 0, 0, 0, 1, 0.9, 0.7, 0.5, -33000, -33000, -33000, 14, &C0, &C1, &C2, &C3, &C4, &C6, &C5, &C7);
- 3rd order non-linearity and 2nd order temperature compensation (8 points for sensor and 3 points for temperature)
 ZMD31050_cal1 (data #1, data #2, data #4, data #3, data #5, data #6, data #7, data #8, 0.1, 0.9, 0.7, 0.5, temp#1, temp#2, temp#3, 14, &C0, &C1, &C2, &C3, &C4, &C6, &C5, &C7);
 TQuad (temp#1, temp#2, temp#3, 0.27, 0.71, 0.42, 14, &Ct0, &Ct1, &Ct2);

2.4. EEPROM Programming

Programming of the SSC IC can be done via the Evaluation Software provided for each SSC IC. Software can be downloaded from the product pages on <u>www.IDT.com</u>.

Refer to the *Evaluation Kit Description* for the SSC IC for further details.

2.5. Verification

Figure 2.5 Calculation and Measurement Results

Calibration coeffs succes c0= 318/013E	sful calculated.	Measure	Digital Out	
c1= 3925/0F55			070	
c2=-17068/BD54			372	
c3= 8367/20AF				
c4= -89/FFA7		□ °C		
c5= -191/FF41				Tmin, °C: -40
c6=-1206/FB4A			676	Tmax °C: 125
c7=-2601/F5D7		J J	676	Target Min [%]: 10 Target Max [%]: 90
ct0=-2865/F4CF				
ct1=-5066/EC36		Measure	The spinst or 11 Million	X
ct2=19915/4DCB			D: 1 10 1	1.0
		v normalize [%]	Digital Out	Log
digitalPGain= 4.099			^^ /	
digitalPGain= 4.099		90	.00%	
2]	.00%	
2	ice or <cancel> for rejectio</cancel>]	.00%	
2	ce or <cancel> for rejectio</cancel>	on		Tmin, °C: 40
2	ce or <cancel> for rejectio</cancel>	on	.00% .09°C	

After successful calibration, the output of the SSC IC should vary between the target limits specified during calibration. For digital data, the readout values match the resolution of the data format used.

For analog output, the output voltage is generated using a resistor-string digital-to-analog converter (DAC) with 5632 steps, of which 5120 steps (256 to 5375) can be addressed. As a result, an adjustable range from 5% to 95% of the supply voltage is guaranteed, including all possible tolerances.

Visit IDT's website <u>www.IDT.com</u> or contact your nearest sales office for the latest version of various support documents.

3 Glossary

Term	Description
ADC	Analog-to-Digital Converter
DAC	Digital to Analog Converter
DLL	Dynamic-Link Library
SSC	Sensor Signal Conditioner

4 Document Revision History

Revision	Date	Description
1.00	July 9, 2015	First release.
	April 26, 2016	Changed to IDT branding.

Notice

- 1. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation or any other use of the circuits, software, and information in the design of your product or system. Renesas Electronics disclaims any and all liability for any losses and damages incurred by you or third parties arising from the use of these circuits, software, or information.
- Renesas Electronics hereby expressly disclaims any warranties against and liability for infringement or any other claims involving patents, copyrights, or other intellectual property rights of third parties, by or arising from the use of Renesas Electronics products or technical information described in this document, including but not limited to, the product data, drawings, charts, programs, algorithms, and application examples.
- 3. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
- 4. You shall be responsible for determining what licenses are required from any third parties, and obtaining such licenses for the lawful import, export, manufacture, sales, utilization, distribution or other disposal of any products incorporating Renesas Electronics products, if required.
- 5. You shall not alter, modify, copy, or reverse engineer any Renesas Electronics product, whether in whole or in part. Renesas Electronics disclaims any and all liability for any losses or damages incurred by you or third parties arising from such alteration, modification, copying or reverse engineering.
- 6. Renesas Electronics products are classified according to the following two quality grades: "Standard" and "High Quality". The intended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below.
 - "Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; industrial robots; etc.

"High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control (traffic lights); large-scale communication equipment; key financial terminal systems; safety control equipment; etc.

Unless expressly designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not intended or authorized for use in products or systems that may pose a direct threat to human life or bodily injury (artificial life support devices or systems; surgical implantations; etc.), or may cause serious property damage (space system; undersea repeaters; nuclear power control systems; aircraft control systems; key plant systems; military equipment; etc.). Renesas Electronics disclaims any and all liability for any damages or losses incurred by you or any third parties arising from the use of any Renesas Electronics product that is inconsistent with any Renesas Electronics data sheet, user's manual or other Renesas Electronics document.

- 7. No semiconductor product is absolutely secure. Notwithstanding any security measures or features that may be implemented in Renesas Electronics hardware or software products, Renesas Electronics shall have absolutely no liability arising out of any vulnerability or security breach, including but not limited to any unauthorized access to or use of a Renesas Electronics product or a system that uses a Renesas Electronics product. RENESAS ELECTRONICS DOES NOT WARRANT OR GUARANTEE THAT RENESAS ELECTRONICS PRODUCTS, OR ANY SYSTEMS CREATED USING RENESAS ELECTRONICS PRODUCTS WILL BE INVULNERABLE OR FREE FROM CORRUPTION, ATTACK, VIRUSES, INTERFERENCE, HACKING, DATA LOSS OR THEFT, OR OTHER SECURITY INTRUSION ("Vulnerability Issues"). RENESAS ELECTRONICS DISCLAIMS ANY AND ALL RESPONSIBILITY OR LIABILITY ARISING FROM OR RELATED TO ANY VULNERABILITY ISSUES. FURTHERMORE, TO THE EXTENT PERMITTED BY APPLICABLE LAW, RENESAS ELECTRONICS DISCLAIMS ANY AND ALL WARRANTIES, EXPRESS OR IMPLIED, WITH RESPECT TO THIS DOCUMENT AND ANY RELATED OR ACCOMPANYING SOFTWARE OR HARDWARE, INCLUDING BUT NOT LIMITED TO THE IMPLIED WARRANTIES OF MERCHANTABILITY, OR FITNESS FOR A PARTICULAR PURPOSE.
- 8. When using Renesas Electronics products, refer to the latest product information (data sheets, user's manuals, application notes, "General Notes for Handling and Using Semiconductor Devices" in the reliability handbook, etc.), and ensure that usage conditions are within the ranges specified by Renesas Electronics with respect to maximum ratings, operating power supply voltage range, heat dissipation characteristics, installation, etc. Renesas Electronics disclaims any and all liability for any malfunctions, failure or accident arising out of the use of Renesas Electronics products outside of such specified ranges.
- 9. Although Renesas Electronics endeavors to improve the quality and reliability of Renesas Electronics products, semiconductor products have specific characteristics, such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Unless designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not subject to radiation resistance design. You are responsible for implementing safety measures to guard against the possibility of bodily injury, injury or damage caused by fire, and/or danger to the public in the event of a failure or malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult and impractical, you are responsible for systems manufactured by you.
- 10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. You are responsible for carefully and sufficiently investigating applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive, and using Renesas Electronics products in compliance with all these applicable laws and regulations. Renesas Electronics disclaims any and all liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
- 11. Renesas Electronics products and technologies shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations. You shall comply with any applicable export control laws and regulations promulgated and administered by the governments of any countries asserting jurisdiction over the parties or transactions.
- 12. It is the responsibility of the buyer or distributor of Renesas Electronics products, or any other party who distributes, disposes of, or otherwise sells or transfers the product to a third party, to notify such third party in advance of the contents and conditions set forth in this document.
- 13. This document shall not be reprinted, reproduced or duplicated in any form, in whole or in part, without prior written consent of Renesas Electronics.
- 14. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products.
- (Note1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its directly or indirectly controlled subsidiaries.
- (Note2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

(Disclaimer Rev.5.0-1 October 2020)

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan www.renesas.com

Contact Information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit: www.renesas.com/contact/

Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.